

<b>Notice of References Cited</b>	Application/Control No. 10/749,152	Applicant(s)/Patent Under Reexamination JOSHI, RAJIV VASANT	
	Examiner Kevin M. Picardat	Art Unit 2822	Page 1 of 2

#### U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,084,412	01-1992	Nakasaka, Yasushi	438/656
	B	US-5,143,820	09-1992	Kotecha et al.	430/314
	C	US-5,173,442	12-1992	Carey, David H.	216/18
	D	US-5,262,354	11-1993	Cote et al.	216/18
	E	US-5,266,446	11-1993	Chang et al.	430/314
	F	US-5,281,854	01-1994	Wong, George	257/740
	G	US-5,300,813	04-1994	Joshi et al.	257/752
	H	US-5,312,509	05-1994	Eschbach, Rudolph J. B.	156/345.31
	I	US-5,345,108	09-1994	Kikkawa, Takamaro	257/751
	J	US-5,356,836	10-1994	Chen et al.	438/627
	K	US-5,399,890	03-1995	Okada et al.	257/306
	L	US-5,442,235	08-1995	Parrillo et al.	257/758
	M	US-5,523,259	06-1996	Merchant et al.	438/643

#### FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

#### NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Y. Arita et al., "CVD Copper Metallurgy for ULSI Interconnections", IEDM 90-93, pp. 3.1.1-3.1.4 (IEEE).
*	V	W. J. Cote et al., "Electroless Plating for Low-Cost High-Leverage Wiring", IBM Technical Disclosure Bulletin V32/#3A, 8/89, pp. 344-345.
*	W	IBM Patent Application S. N. 08/768,107, filed Dec. 16, 1996, "Electroplated Interconnections Structures on Integrated Circuit Chips".
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

<b>Notice of References Cited</b>	Application/Control No. 10/749,152	Applicant(s)/Patent Under Reexamination JOSHI, RAJIV VASANT	
	Examiner Kevin M. Picardat	Art Unit 2822	Page 2 of 2

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,534,463	07-1996	Lee et al.	438/643
	B	US-5,565,707	10-1996	Colgan et al.	257/762
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.